

Features

- Low start-up voltage: 0.7V (Typ.), 0.9V (Max.)
- High efficiency: 85% (Typ.), $V_{OUT} \geq 2.7V$
- High output voltage accuracy: $\pm 2.5\%$
- Output voltage: 1.8V, 2.7V, 3.0V, 3.3V, 3.7V, 5.0V
- Ultra low supply current I_{DD2} : 4 μ A (Typ.)
- Low ripple and low noise
- Low shutdown current: 0.5 μ A (Typ.)
- TO-92, SOT-89, SOT-23 and SOT-25 package

Applications

- Palmtops/PDAs
- Portable communicators/Smartphones
- Cameras/Camcorders
- Battery-powered equipment

General Description

The HT77XX series is a set of PFM step-up DC/DC converter with high efficiency and low ripple. The series features extremely low start-up voltage and high output voltage accuracy. They require only three external components to provide a fixed output voltage of 1.8V, 2.7V, 3.0V, 3.3V, 3.7V or 5.0V. CMOS technology ensures ultra low supply current and makes them ideal for battery-operated applications powered from one or more cells.

The HT77XX consists of an oscillator, a PFM control circuit, a driver transistor, a reference voltage unit, and a high speed comparator. They employ pulse frequency modulation (PFM) for minimum supply current and ripple at light output loading. These devices are available in space saving TO-92, SOT-89, SOT-23 and SOT-25 packages. For SOT-25 package, it also build-in a chip enable function to reduce power consumption during shutdown mode.

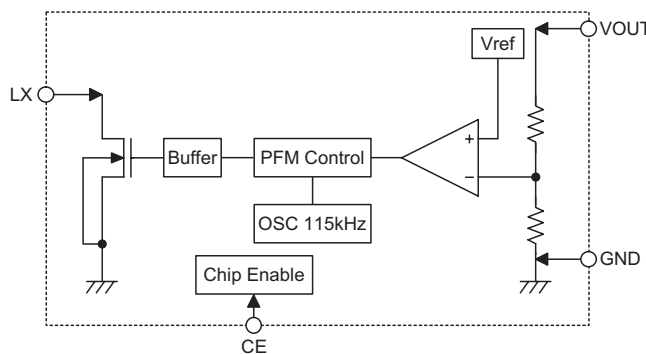
Selection Table

Part No.	Output Voltage	Package	Marking
HT7718	1.8V	TO-92 SOT-89 SOT-23 SOT-25	HT77XX (for TO-92) HT77XX# (for SOT-89) 77XX# (for SOT-23) 77XX# (for SOT-25)
HT7727	2.7V		
HT7730	3.0V		
HT7733	3.3V		
HT7737	3.7V		
HT7750	5.0V		

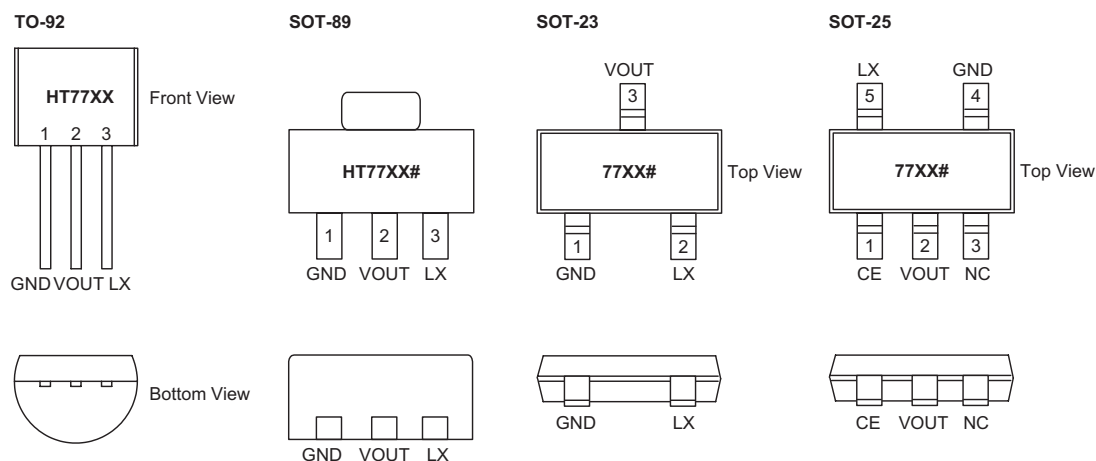
Note: "XX" stands for output voltages.

Only lead free devices are available. "#" stands for lead free devices. For the TO-92 package, there will be a "#" mark at the end of the date code.

Block Diagram



Pin Assignment



Pin Description

Pin No.				Pin Name	Description
TO-92	SOT-89	SOT-23	SOT-25		
—	—	—	1	CE	Chip enable pin, high active
2	2	3	2	VOUT	DC/DC converter output monitoring pin
—	—	—	3	NC	No connection
1	1	1	4	GND	Ground pin
3	3	2	5	LX	Switching pin

Absolute Maximum Ratings

Supply Voltage $V_{SS} - 0.3V$ to $V_{SS} + 7V$ Storage Temperature $-50^{\circ}C$ to $125^{\circ}C$
 Operating Temperature $-40^{\circ}C$ to $85^{\circ}C$

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Thermal Information

Symbol	Parameter	Package	Max.	Unit
θ_{JA}	Thermal Resistance (Junction to Ambient) (Assume no ambient airflow, no heat sink)	SOT-89	300	$^{\circ}C/W$
		TO-92	300	$^{\circ}C/W$
		SOT-23	330	$^{\circ}C/W$
		SOT-25	320	$^{\circ}C/W$
P_D	Power Dissipation	SOT-89	0.33	W
		TO-92	0.33	W
		SOT-23	0.3	W
		SOT-25	0.31	W

Note: P_D is measured at $T_a = 25^{\circ}C$

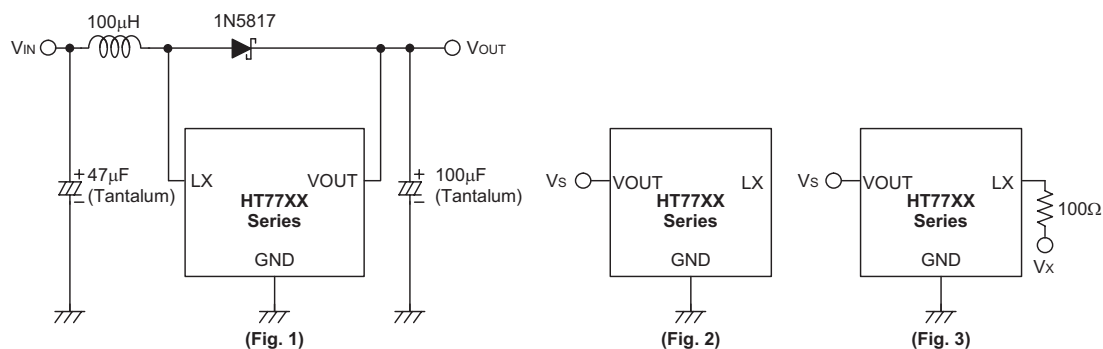
Electrical Characteristics

$V_{IN}=V_{OUT}\times 0.6$; $I_{OUT}=10\text{mA}$; $T_a=25^\circ\text{C}$ (Unless otherwise specified)

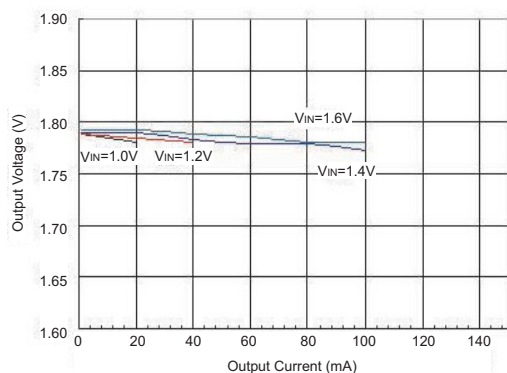
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{IN}	Input Voltage	—	—	—	6	V
ΔV_{OUT}	Output Voltage Tolerance	—	-2.5	—	2.5	%
V_{START}	Start-up Voltage (Fig. 1)	V_{IN} : 0→2V; $I_{OUT}=1\text{mA}$	—	0.7	0.9	V
V_{HOLD}	Minimum Hold-on Voltage (Fig. 1)	V_{IN} : 2→0V; $I_{OUT}=1\text{mA}$	—	—	0.7	V
I_{IN}	No-load Input Current (Fig. 1)	$I_{OUT}=0\text{mA}$	—	10	20	μA
I_{DD1}	Supply Current 1 (Fig. 2)	$V_S=V_{OUT}\times 0.95$ Measured at V_{OUT} pin	$V_{OUT}=1.8\text{V}$	—	35	50
			$V_{OUT}=2.7\text{V}$	—	40	60
			$V_{OUT}=3.0\text{V}$	—	45	68
			$V_{OUT}=3.3\text{V}$	—	55	81
			$V_{OUT}=3.7\text{V}$	—	64	85
			$V_{OUT}=5.0\text{V}$	—	85	134
I_{DD2}	Supply Current 2 (Fig. 2)	$V_S=V_{OUT}+0.5\text{V}$ Measured at V_{OUT} pin	—	4	7	μA
I_{SHDN}	Shutdown Current	$CE=GND$	—	0.5	1	μA
V_{IH}	CE High Threshold	—	2	—	—	V
V_{IL}	CE Low Threshold	—	—	—	0.4	V
I_{LEAK}	LX Leakage Current (Fig. 3)	$V_S=V_{OUT}+0.5\text{V}$, $V_X=6\text{V}$ Measured at the LX pin	—	—	0.9	μA
f_{OSC}	Maximum Oscillator Frequency (Fig. 3)	$V_S=V_{OUT}\times 0.95$ Measured at LX pin	—	115	—	kHz
D_{OSC}	Oscillator Duty Cycle (Fig. 3)	$V_S=V_{OUT}\times 0.95$ Measured at LX pin	65	75	85	%
η	Efficiency	$V_{OUT}\leq 1.8\text{V}$	—	80	—	%
		$V_{OUT}\geq 2.7\text{V}$	—	85	—	

Note: Absolute maximum ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. The guaranteed specifications apply only for the test conditions listed.

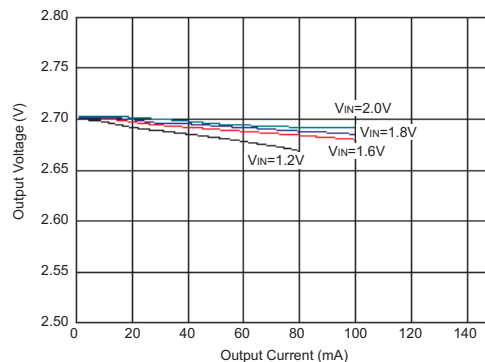
Test Circuit



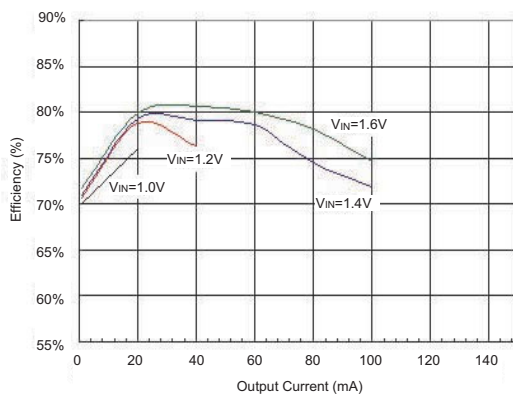
Typical Performance Characteristics



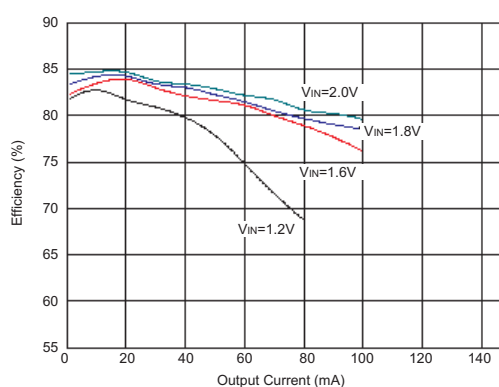
HT7718 Output Voltage v.s Output Current



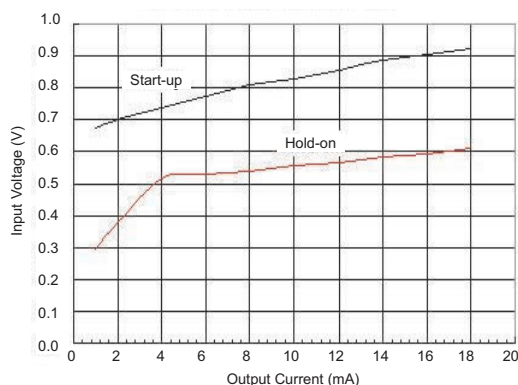
HT7727 Output Voltage v.s Output Current



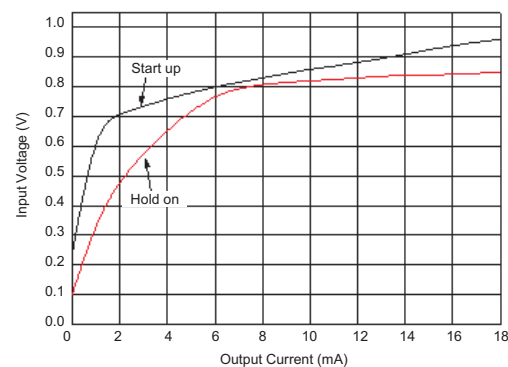
HT7718 Efficiency v.s Output Current



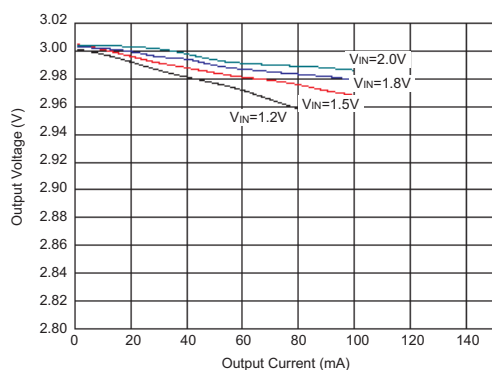
HT7727 Efficiency v.s Output Current



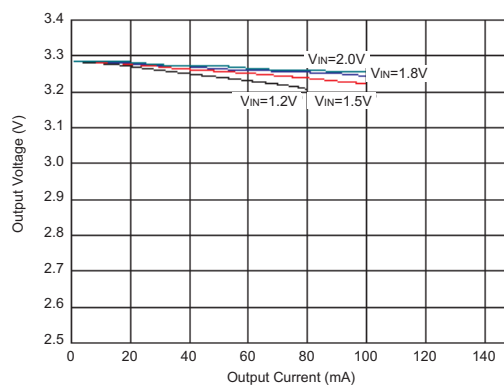
HT7718 Start-Up & Hold-On Voltage



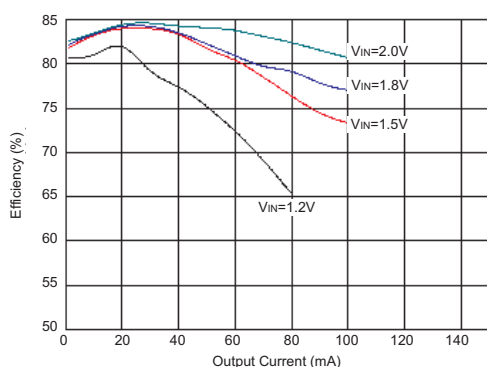
HT7727 Start-Up & Hold-On Voltage



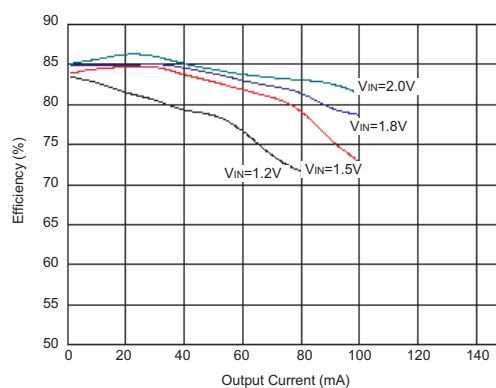
HT7730 Output Voltage v.s Output Current



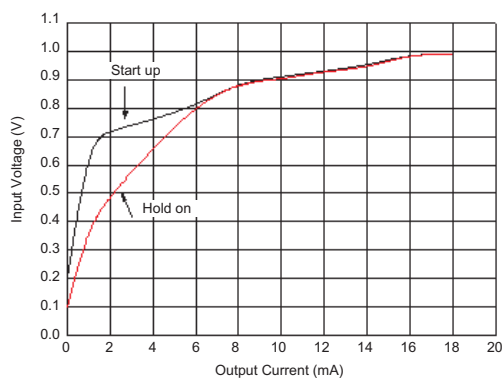
HT7733 Output Voltage v.s Output Current



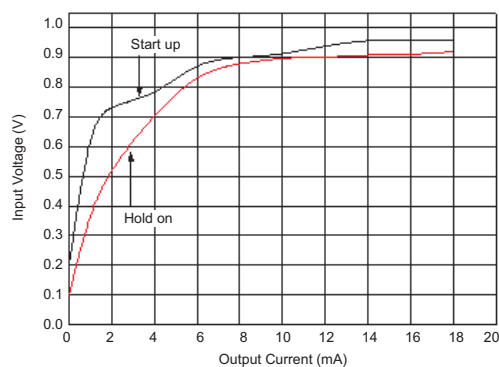
HT7730 Efficiency v.s Output Current



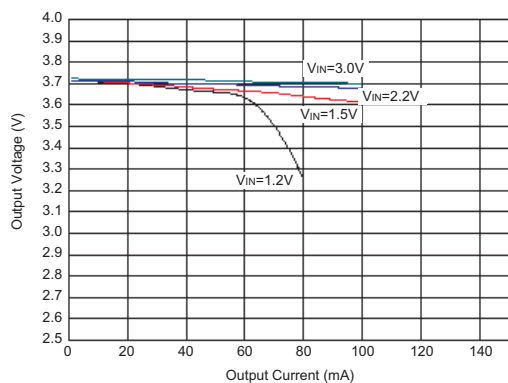
HT7733 Efficiency v.s Output Current



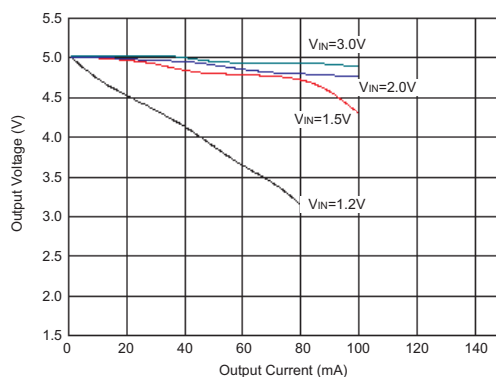
HT7730 Start-Up & Hold-On Voltage



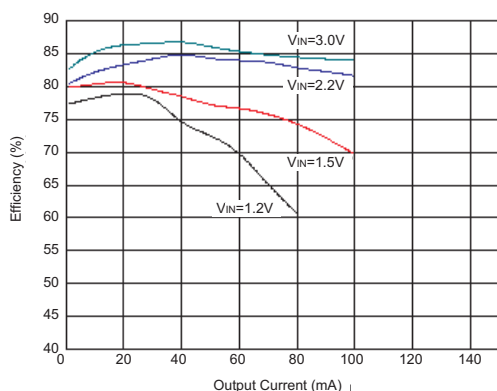
HT7733 Start-Up & Hold-On Voltage



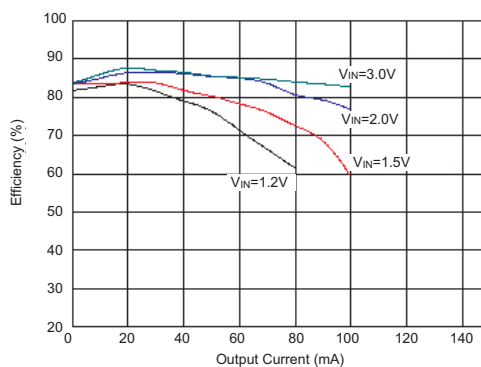
HT7737 Output Voltage v.s Output Current



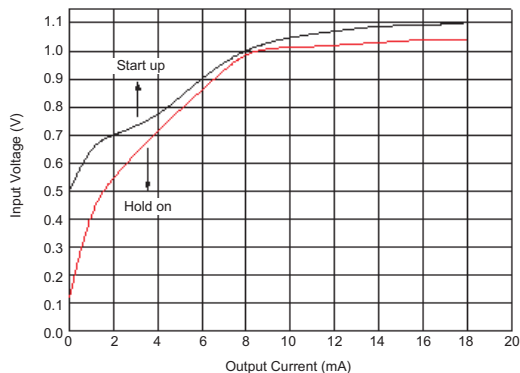
HT7750 Output Voltage v.s Output Current



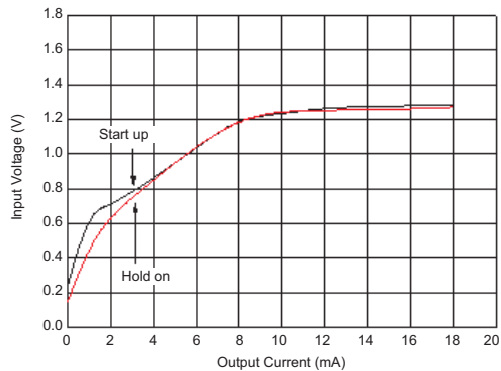
HT7737 Efficiency v.s Output Current



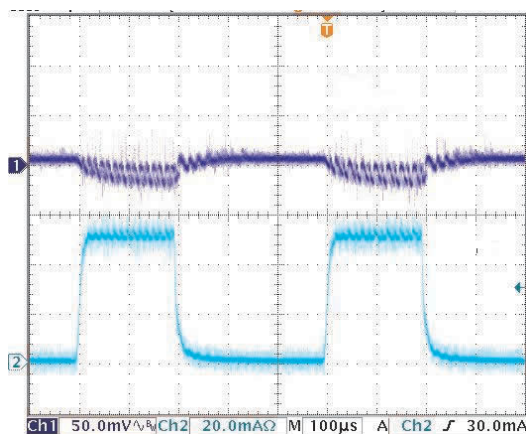
HT7750 Efficiency v.s Output Current



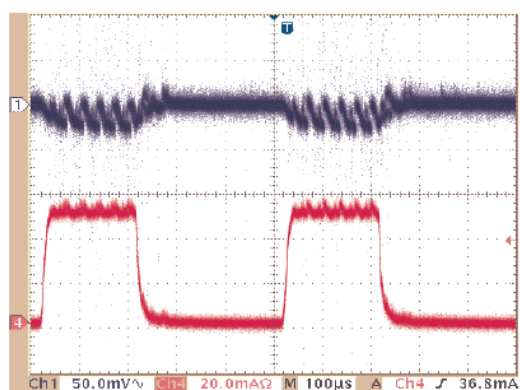
HT7737 Start-Up& Hold-On Voltage



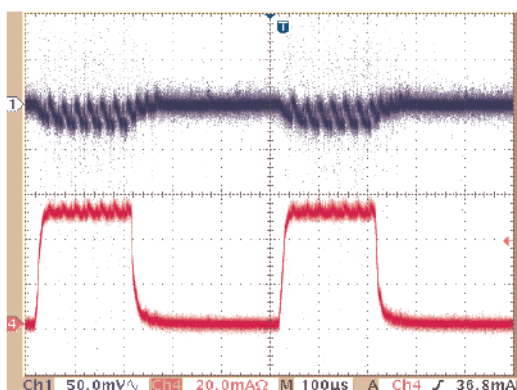
HT7750 Start-Up& Hold-On Voltage



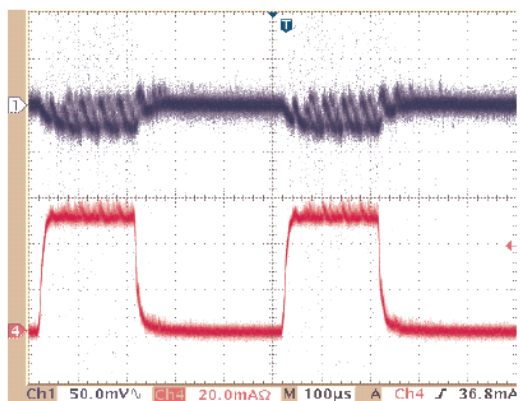
HT7718 Load Transient Response
($L=100\mu\text{H}$, $C_{\text{OUT}}=100\mu\text{F}$, $V_{\text{IN}}=1.08\text{V}$)



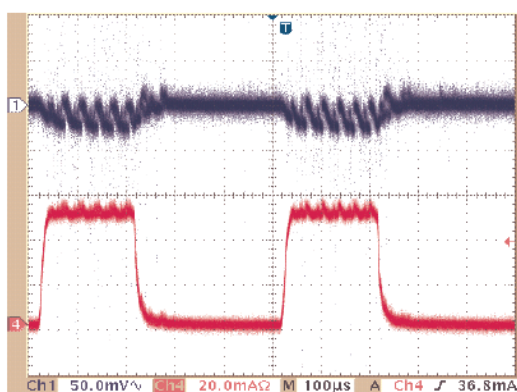
HT7733 Load Transient Response
($L=100\mu\text{H}$, $C_{\text{OUT}}=100\mu\text{F}$, $V_{\text{IN}}=1.98\text{V}$)



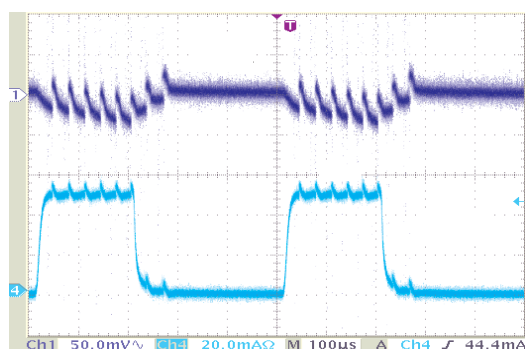
HT7727 Load Transient Response
($L=100\mu\text{H}$, $C_{\text{OUT}}=100\mu\text{F}$, $V_{\text{IN}}=1.62\text{V}$)



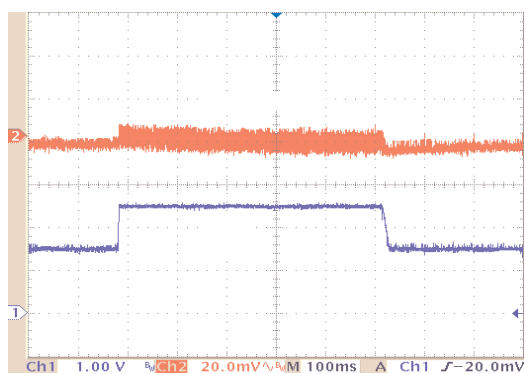
HT7737 Load Transient Response
($L=100\mu\text{H}$, $C_{\text{OUT}}=100\mu\text{F}$, $V_{\text{IN}}=2.22\text{V}$)



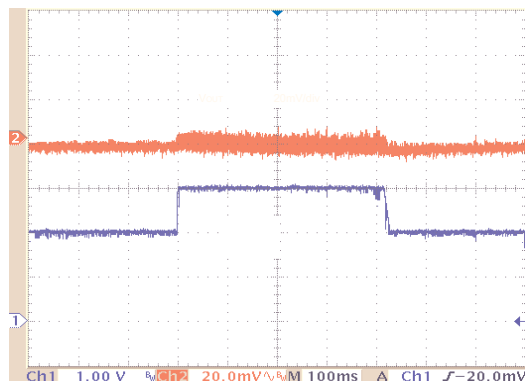
HT7730 Load Transient Response
($L=100\mu\text{H}$, $C_{\text{OUT}}=100\mu\text{F}$, $V_{\text{IN}}=1.8\text{V}$)



HT7750 Load Transient Response
($L=100\mu\text{H}$, $C_{\text{OUT}}=100\mu\text{F}$, $V_{\text{IN}}=3\text{V}$)



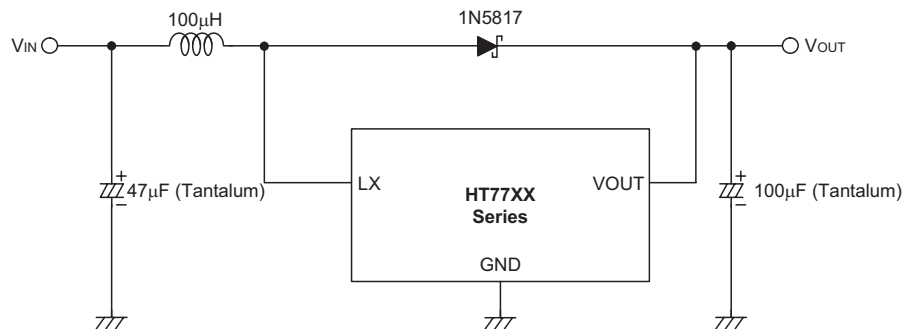
HT7733 Line Transient Response
($L=100\mu\text{H}$, $C_{OUT}=100\mu\text{F}$)



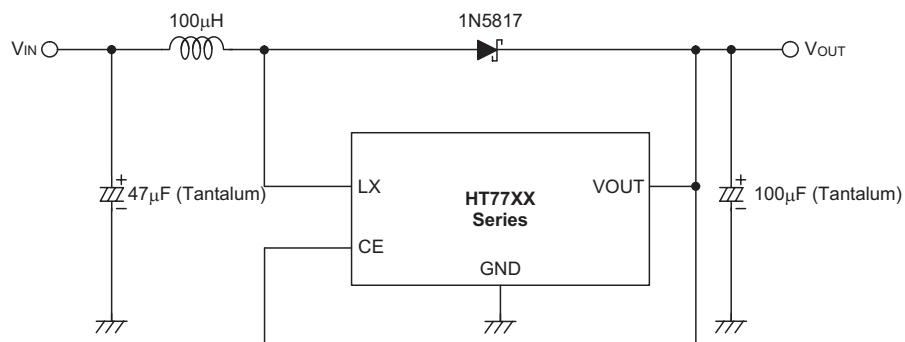
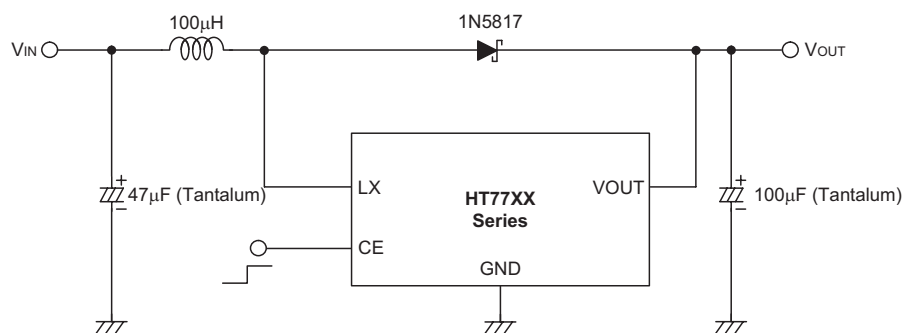
HT7750 Line Transient Response
($L=100\mu\text{H}$, $C_{OUT}=100\mu\text{F}$)

Application Circuits

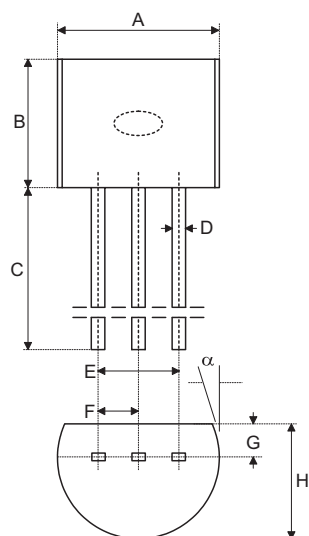
Without CE Pin



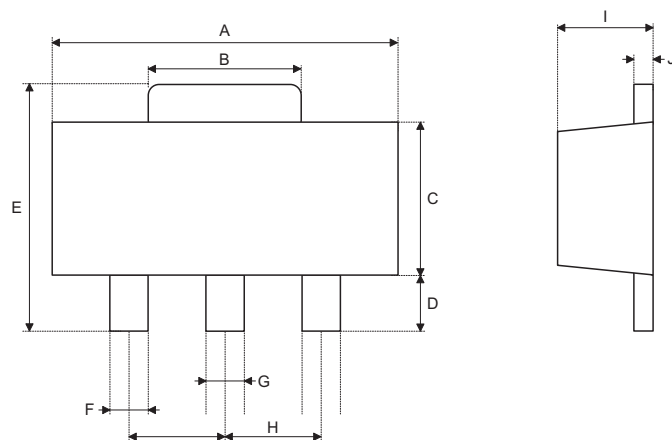
With CE Pin



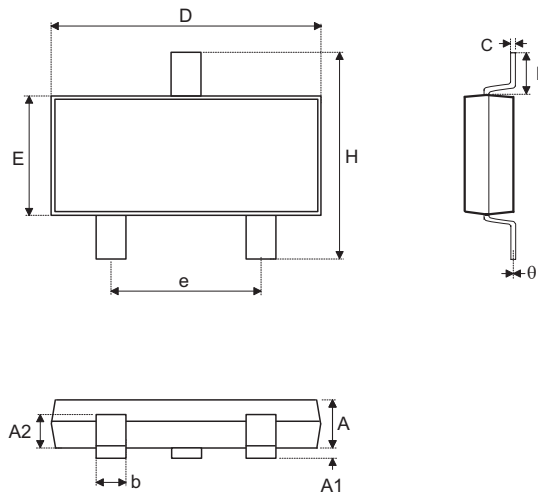
Note: For the SOT-25 package, when CE is pulled low, the internal blocks of the device, such as the reference band gap, gain block, and all feedback and control circuitry will be switched off. The boost converter's output, V_{OUT} , will be at a value one Schottky diode voltage drop below the input voltage and the LX pin remains in a high impedance condition. The output capacitor and load at V_{OUT} determine the rate at which V_{OUT} decays.

Package Information
3-pin TO-92 Outline Dimensions


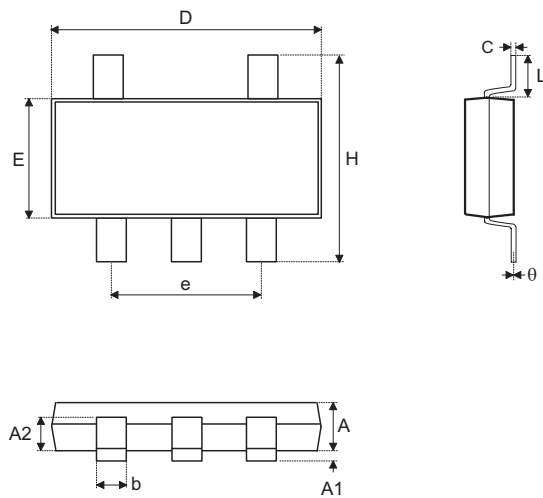
Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	170	—	200
B	170	—	200
C	500	—	—
D	11	—	20
E	90	—	110
F	45	—	55
G	45	—	65
H	130	—	160
I	8	—	18
α	4°	—	6°

3-pin SOT-89 Outline Dimensions


Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	173	—	181
B	64	—	72
C	90	—	102
D	35	—	47
E	155	—	167
F	14	—	19
G	17	—	22
H	—	59	—
I	55	—	63
J	14	—	17

3-pin SOT-23 Outline Dimensions


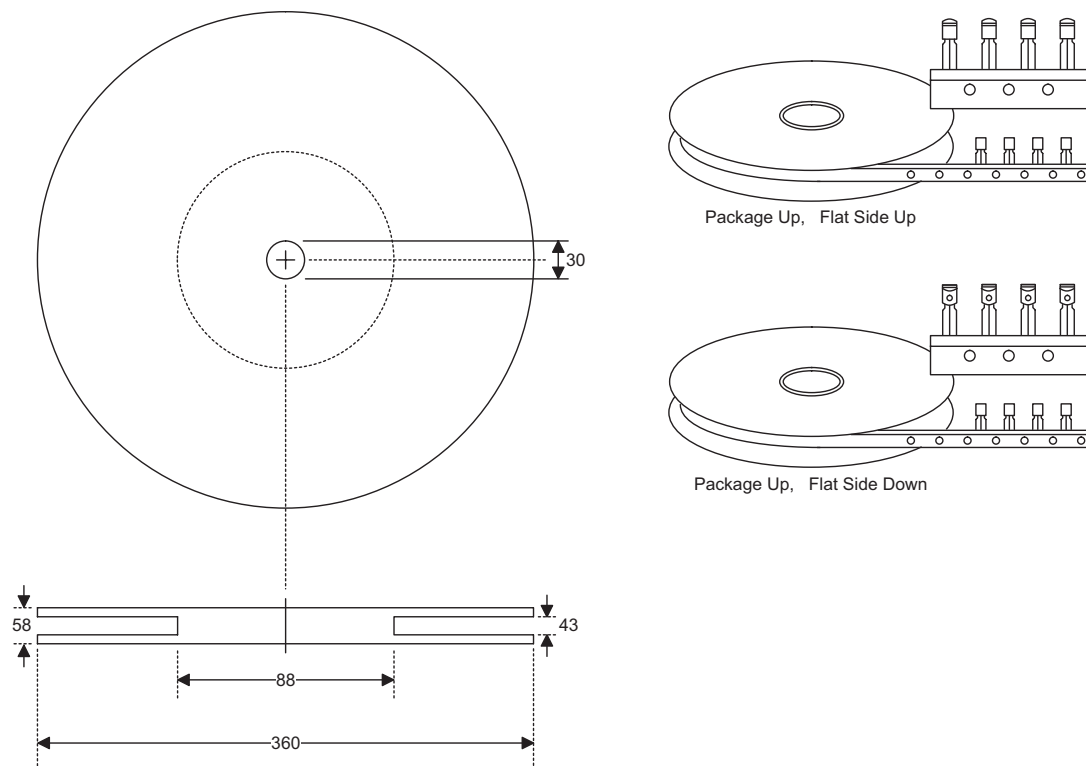
Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	1	—	1.3
A1	—	—	0.1
A2	0.7	—	0.9
b	0.35	—	0.5
C	0.1	—	0.25
D	2.7	—	3.1
E	1.4	—	1.8
e	—	1.9	—
H	2.6	—	3
L	0.37	—	—
θ	1°	—	9°

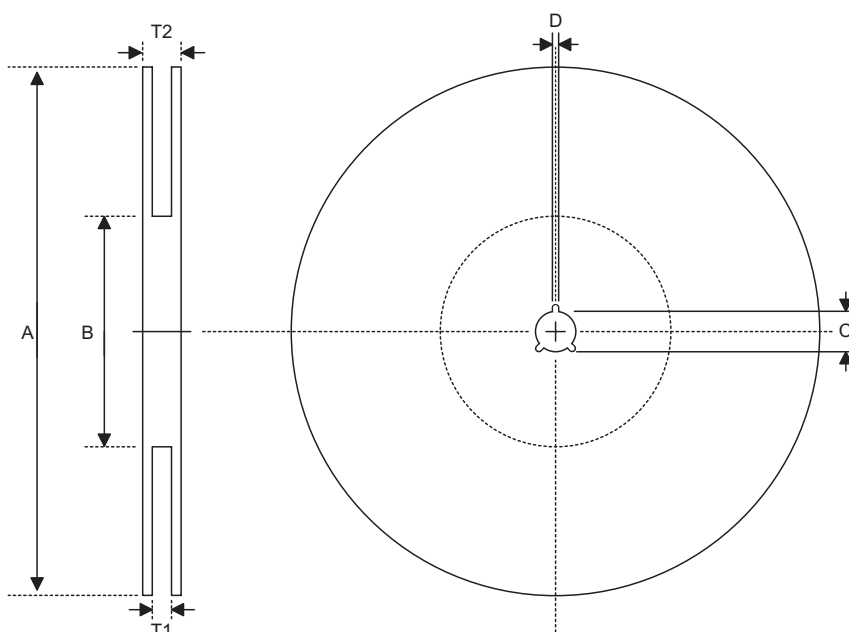
5-pin SOT-25 Outline Dimensions


Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	1.00	—	1.30
A1	—	—	0.10
A2	0.70	—	0.90
b	0.35	—	0.50
C	0.10	—	0.25
D	2.70	—	3.10
E	1.40	—	1.80
e	—	1.90	—
H	2.60	—	3
L	0.37	—	—
θ	1°	—	9°

Product Tape and Reel Specifications

TO-92 Reel Dimensions (Unit: mm)



SOT-89, SOT-23 & SOT-25 Reel Dimensions

SOT-89

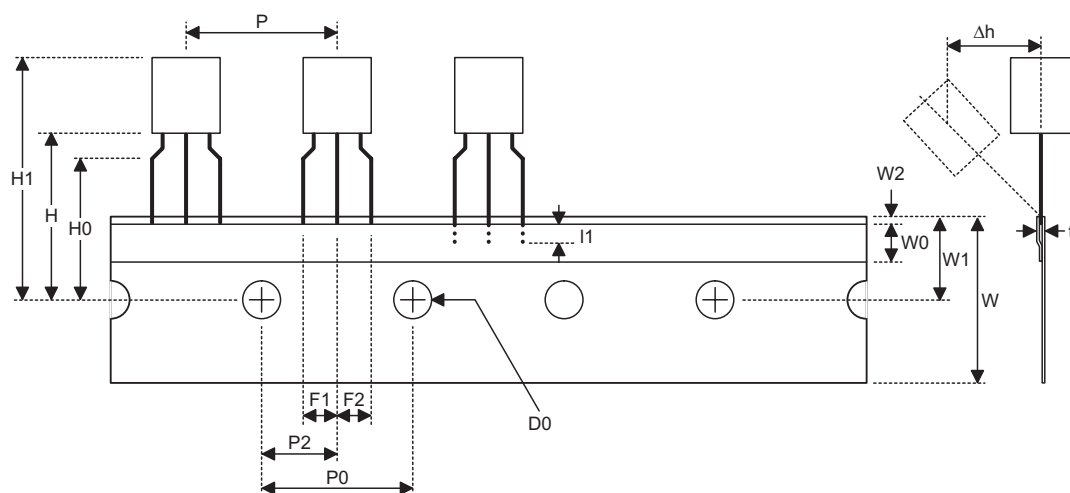
Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	180±1.0
B	Reel Inner Diameter	62±1.5
C	Spindle Hole Diameter	12.75±0.15
D	Key Slit Width	1.9±0.15
T1	Space Between Flange	12.4±0.2
T2	Reel Thickness	17-0.4

SOT-23

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	178±1
B	Reel Inner Diameter	62±1
C	Spindle Hole Diameter	13±0.2
D	Key Slit Width	2.5±0.25
T1	Space Between Flange	8.4±1.5
T2	Reel Thickness	11.4±1.5

SOT-25

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	178±1.0
B	Reel Inner Diameter	62±1.0
C	Spindle Hole Diameter	13.0±0.2
D	Key Slit Width	2.5±0.25
T1	Space Between Flange	8.4±1.5 -0.0
T2	Reel Thickness	11.4±1.5

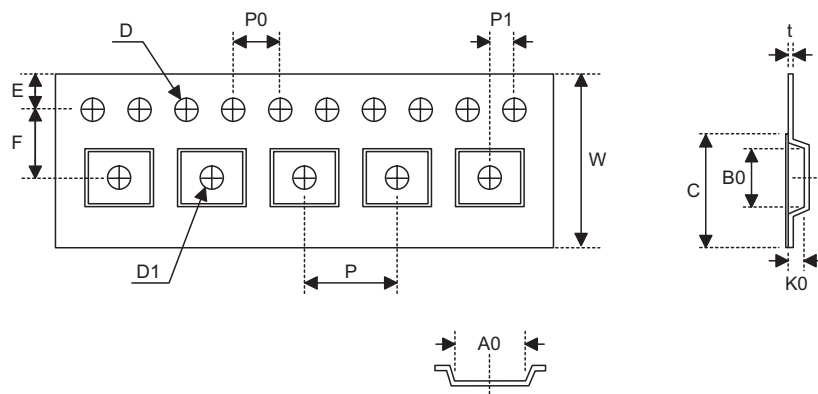
TO-92 Carrier Tape Dimensions

TO-92

Symbol	Description	Dimensions in mm
l1	Taped Lead Length	(2.5)
P	Component Pitch	12.7±1.0
P ₀	Perforation Pitch	12.7±0.3
P ₂	Component to Perforation (Length Direction)	6.35±0.4
F ₁	Lead Spread	2.5+0.4 -0.1
F ₂	Lead Spread	2.5+0.4 -0.1
Δh	Component Alignment	0±0.1
W	Carrier Tape Width	18.0+1.0 -0.5
W ₀	Hold-down Tape Width	6.0±0.5
W ₁	Perforation Position	9.0±0.5
W ₂	Hold-down Tape Position	(0.5)
H ₀	Lead Clinch Height	16.0±0.5
H ₁	Component Height	Less than 24.7
D ₀	Perforation Diameter	4.0±0.2
t	Taped Lead Thickness	0.7±0.2
H	Component Base Height	19.0±0.5

Note: Thickness less than 0.38±0.05mm~0.5mm

P0 Accumulated pitch tolerance: ±1mm/20pitches.

() Bracketed figures are for reference only.

SOT-89, SOT-23 & SOT-25 Carrier Tape Dimensions

SOT-89

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0+0.3 -0.1
P	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.05
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.1
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.10
A0	Cavity Length	4.8±0.1
B0	Cavity Width	4.5±0.1
K0	Cavity Depth	1.8±0.1
t	Carrier Tape Thickness	0.30±0.013
C	Cover Tape Width	9.3

SOT-23

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	8±0.3
P	Cavity Pitch	4
E	Perforation Position	1.75
F	Cavity to Perforation (Width Direction)	3.5±0.05
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.1
P0	Perforation Pitch	4
P1	Cavity to Perforation (Length Direction)	2
A0	Cavity Length	3.15
B0	Cavity Width	3.2
K0	Cavity Depth	1.4
t	Carrier Tape Thickness	0.2±0.03
C	Cover Tape Width	5.3

SOT-25

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	8.0±0.3
P	Cavity Pitch	4.0
E	Perforation Position	1.75
F	Cavity to Perforation (Width Direction)	3.5±0.05
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.1
P0	Perforation Pitch	4.0
P1	Cavity to Perforation (Length Direction)	2.0
A0	Cavity Length	3.15
B0	Cavity Width	3.2
K0	Cavity Depth	1.4
t	Carrier Tape Thickness	0.20±0.03
C	Cover Tape Width	5.3

Holtek Semiconductor Inc. (Headquarters)

No.3, Creation Rd. II, Science Park, Hsinchu, Taiwan
Tel: 886-3-563-1999
Fax: 886-3-563-1189
<http://www.holtek.com.tw>

Holtek Semiconductor Inc. (Taipei Sales Office)

4F-2, No. 3-2, YuanQu St., Nankang Software Park, Taipei 115, Taiwan
Tel: 886-2-2655-7070
Fax: 886-2-2655-7373
Fax: 886-2-2655-7383 (International sales hotline)

Holtek Semiconductor Inc. (Shanghai Sales Office)

7th Floor, Building 2, No.889, Yi Shan Rd., Shanghai, China 200233
Tel: 86-21-6485-5560
Fax: 86-21-6485-0313
<http://www.holtek.com.cn>

Holtek Semiconductor Inc. (Shenzhen Sales Office)

5/F, Unit A, Productivity Building, Cross of Science M 3rd Road and Gaoxin M 2nd Road, Science Park, Nanshan District, Shenzhen, China 518057
Tel: 86-755-8616-9908, 86-755-8616-9308
Fax: 86-755-8616-9722

Holtek Semiconductor Inc. (Beijing Sales Office)

Suite 1721, Jinyu Tower, A129 West Xuan Wu Men Street, Xicheng District, Beijing, China 100031
Tel: 86-10-6641-0030, 86-10-6641-7751, 86-10-6641-7752
Fax: 86-10-6641-0125

Holtek Semiconductor Inc. (Chengdu Sales Office)

709, Building 3, Champagne Plaza, No.97 Dongda Street, Chengdu, Sichuan, China 610016
Tel: 86-28-6653-6590
Fax: 86-28-6653-6591

Holtek Semiconductor (USA), Inc. (North America Sales Office)

46729 Fremont Blvd., Fremont, CA 94538
Tel: 1-510-252-9880
Fax: 1-510-252-9885
<http://www.holtek.com>

Copyright © 2007 by HOLTEK SEMICONDUCTOR INC.

The information appearing in this Data Sheet is believed to be accurate at the time of publication. However, Holtek assumes no responsibility arising from the use of the specifications described. The applications mentioned herein are used solely for the purpose of illustration and Holtek makes no warranty or representation that such applications will be suitable without further modification, nor recommends the use of its products for application that may present a risk to human life due to malfunction or otherwise. Holtek's products are not authorized for use as critical components in life support devices or systems. Holtek reserves the right to alter its products without prior notification. For the most up-to-date information, please visit our web site at <http://www.holtek.com.tw>.